PRELIMINARY



RFM products are now Murata products.

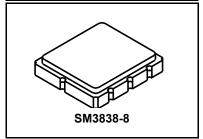
SF2346D

- · Designed for Front End GPS Applications
- Steep Rejection
- 3.8 x 3.8 x 1.2 mm Surface-Mount Case
- · No Matching Circuit Required

Absolute Maximum Ratings

Rating	Value	Units	
Maximum Input Power	+20	dBm	
Maximum DC Voltage On any Non-ground Terminal	0	VDC	
Storage Temperature Range	-40 to +85	°C	
Operating Temperature Range	0 to +40	°C	
Maximum Soldering Profile (5 cycles maximum)	265 °C for 10 s		

924.375 MHz **SAW Filter**

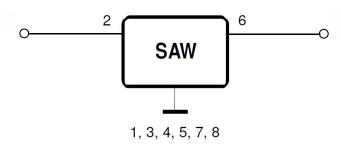


Electrical Characteristics

Characteristic	Sym	Notes	Min	Тур	Max	Units
Center Frequency	f _C			924.375		MHz
Insertion Loss (920.925 to 927.825 MHz)	IL			2.5	3	dB
1dB Bandwidth (7	10		MHz
Amplitude Ripple, (920.925 to 927.825 MHz)				0.6	1.0	dB
Attenuation relative to IL						
10 to 914.8 MHz			7	12		dB
940 to 1500 MHz			30	35		
VSWR (920.925 to 927.825 MHz)			1.9	2.2		
Ambient Temperature				25		
Source impedance	Z _S			50		Ω
Load impedance	Z _I			50		Ω

Case Style	SMD 3.8 x 3.8			
Lid Symbolization	B30			

Connection	Terminal
Input	2
Output	6
Ground	All others



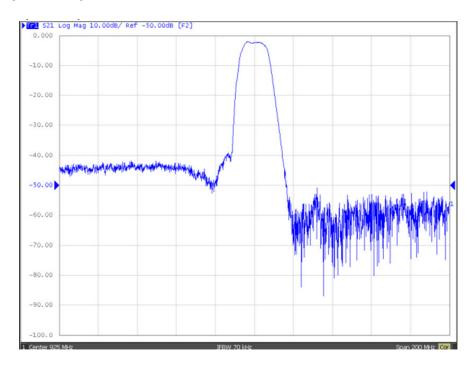


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling. NOTES:

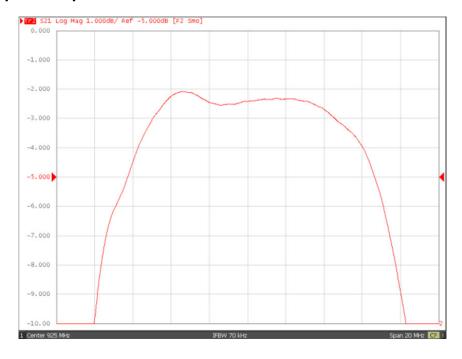
- US and international patents may apply. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.

Frequency Characteristics

S21 Response: Span - 200 MHz

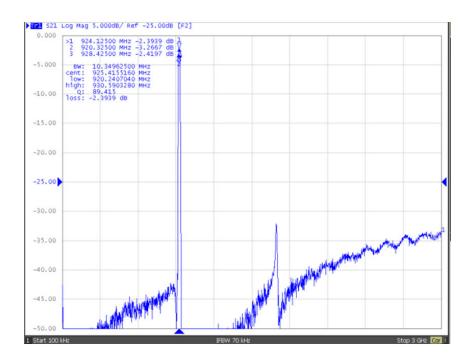


S21 Response: Span - 20 MHz

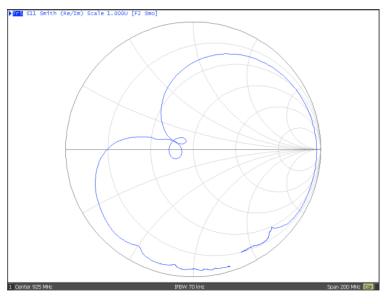


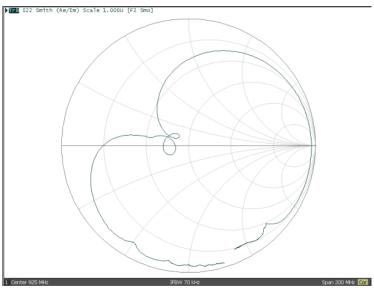
Frequency Characteristics

S21 Response: Span - 100 KHz - 3 GHz



S11/S22 Response

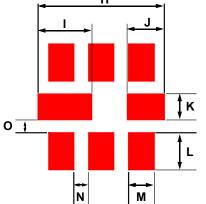




SM3838-8 Case

8-Terminal Ceramic Surface-Mount Case 3.8 X 3.8 mm Nominal Footprint

H H



PCB Footprint

Case and PCB Footprint Dimensions

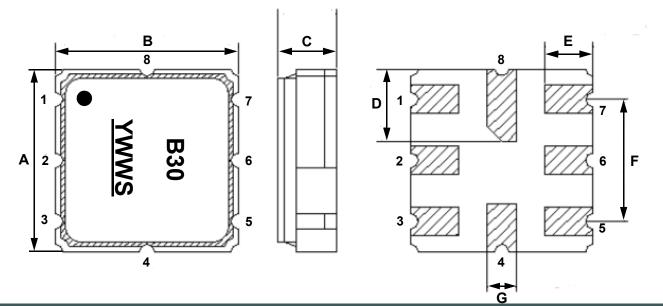
Dimension	Dimension mm		Inches			
Difficusion	Min	Nom	Max	Min	Nom	Max
Α	3.65	3.80	3.95	0.142	0.150	0.157
В	3.65	3.80	3.95	0.142	0.150	0.157
С	-	-	1.40	-	-	0.047
D	-	1.50	-	-	0.059	-
E	-	1.00	-	-	0.039	-
F	-	2.54	-	-	0.100	-
G	-	0.60	-	-	0.023	-
Н	-	4.01	-	-	0.157	-
I	-	1.70	-	-	0.066	-
J	-	1.19	-	-	0.046	-
K	-	0.81	-	-	0.031	-
L	-	1.19	-	-	0.046	-
М	-	0.81	-	-	0.031	-
N	-	0.46	-	-	0.018	-
0	-	0.41	-		0.016	-

Case Materials

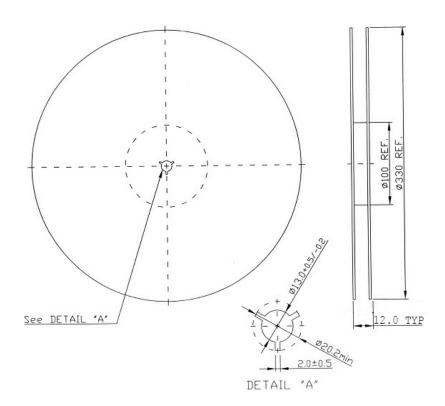
Materials			
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel		
Lid Plating	2.0 to 3.0 µm Nickel		
Body	Al ₂ O ₃ Ceramic		
Pb Free			

TOP VIEW

BOTTOM VIEW



Reel Dimension



Tape Dimension

